



**12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

**PCN# 20251028001.1**

**Qualification of TIPI as additional Assembly site for select devices  
Change Notification / Sample Request**

**Date:** October 28, 2025

**To:** MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team  
SC Business Services

**20251028001.1**  
**Change Notification / Sample Request**  
**Attachments**

**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

<b>DEVICE</b>	<b>CUSTOMER PART NUMBER</b>
SN74LVC1G11DBVRE4	NULL
SN74LVC1G11DBVRG4	NULL
74LVC1GU04DBVRE4	NULL
SN74LVC1G32DBVRG4	SN74LVC1G32DBVRG4

Technical details of this Product Change follow on the next page(s).

<b>PCN Number:</b>	20251028001.1	<b>PCN Date:</b>	October 28, 2025
<b>Title:</b>	Qualification of TIPI as an additional Assembly site for select devices		
<b>Customer Contact:</b>	Change Management team	<b>Dept:</b>	Quality Services
<b>Proposed 1<sup>st</sup> Ship Date:</b>	January 26, 2026	<b>Sample requests accepted until:</b>	December 27, 2025
<b>*Sample requests received after December 27, 2025 will not be supported.</b>			
<b>Change Type:</b>			
<input checked="" type="checkbox"/> Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/> Wafer Bump Material
<input checked="" type="checkbox"/> Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/> Wafer Bump Process
<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/> Wafer Fab Site
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/> Wafer Fab Material
<input checked="" type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/> Wafer Fab Process

### PCN Details

#### Description of Change:

Texas Instruments Incorporated is announcing the qualification of TIPI as an additional Assembly site for devices listed below in the product affected section. Construction differences and current assembly site as follows:

#### Material differences:

	<b>Current</b>	<b>Additional</b>
Assembly site	<b>TFME</b>	<b>TIPI</b>
Wire type/diam	0.8mil Au	0.8mil Cu
Mount Compound	SID# A-03	8095733
Mold Compound	SID#R-13	4222198

#### Marking Differences:

	<b>TFME</b>	<b>TIPI</b>
SN74LVC1G32DBVRG4/E4	C32F	C32J
74LVC1GU04DBVRG4/E4	CU4F	CU4J
SN74AUC1G17DBVRG4	U17F	U17R
SN74AUC1G32DBVRG4	U32F	U32F
SN74LVC1G11DBVRG4/E4	C11F	C11R
SN74LVC2G04DBVRG4/E4	C04F	C04R
SN74LVC2G14DBVRG4/E4	C14F	C14R

#### Reason for Change:

Supply continuity

#### Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

#### Impact on Environmental Ratings:

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

<b>RoHS</b>	<b>REACH</b>	<b>Green Status</b>	<b>IEC 62474</b>
<input checked="" type="checkbox"/> No Change			

## Changes to product identification resulting from this PCN:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
TFME	NFM	CHN	Chongchuan
<b>TIPI</b>	<b>PHI</b>	<b>PHL</b>	<b>Baguio City</b>

Sample product shipping label (not actual product label)



## Product Affected:

74LVC1GU04DBVRG4	SN74LVC1G11DBVRG4	SN74LVC2G04DBVRG4
74LVC1GU04DBVRE4	SN74LVC1G11DBVRE4	SN74LVC2G04DBVRE4
SN74AUC1G17DBVRG4	SN74LVC1G32DBVRG4	SN74LVC2G14DBVRG4
SN74AUC1G32DBVRG4	SN74LVC1G32DBVRE4	SN74LVC2G14DBVRE4

## Automotive Qualification Summary (As per AEC-Q100 Rev. J and JEDEC Guidelines)

Approve Date 17-June-2025

### Product Attributes

Attributes	QBS Process Reference: TIP235AE0BZRQ1	QBS Process Reference: TL431LIB0BZRQ1	QBS Package Reference: TLV2401QDBVRQ1	QBS Package, Process Reference: SN3257QDYYRQ1	QBS Package Reference: TL331BQDDBVRQ1 TL331BQDDBVRQ	QBS Package, Process Reference: TBS3820-50QDDBVRQ1	QBS Package Reference: TSM24CADBZRQ1
Automotive Grade Level	Grade 0	Grade 0	Grade 1	Grade 1	Grade 1	Grade 1	Grade 0
Operating Temp Range (C)	-40 to 150	-40 to 150	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-55 to 150
Product Function	Signal Chain	Power Management	Signal Chain	Logic, Signal Chain	Signal Chain	Power Management	Interface
Wafer Fab Supplier	RFAB	CFAB	DL-LIN	RFAB	CFAB	DL-LIN	CFAB
Assembly Site	HNA	TRME	PHI	PHI	PHI	PHI	PHI
Package Group	SOT	SOT	SOT	SOT	SOT	SOT	SOT
Package Designator	DBZ	DBZ	DBV	DYY	DBV	DBV	DBZ
Pin Count	3	3	5	16	5	5	3

QBS: Qual By Similarity, also known as Generic Data

Note 1: Affected devices in PCN have justification to use Package QBS references for Group A tests based on AEC-100J Appendix 1 A1.3 assembly site and package attributes were qualified.

Note 2: Affected devices in PCN have justification to use Process QBS references for Group B tests based on AEC-100J Appendix 1 A1.2 silicon wafer fab and die attributes were qualified.

Note 3: Affected devices in PCN have justification to use Package QBS for Group C tests based on AEC-100J Appendix 1 A1.3 package wire, leadframe and package group attributes are qualified.

Note 4: ED cannot use Generic data per AEC-Q100J but there is representation of passing Electrical Distributions with the same assembly site and package attributes.

## Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	QBB Process Reference:	QBB Process Reference:	QBB Package Reference:	QBB Package, Process Reference:	QBB Package, Process Reference:	QBB Package Reference:
<b>Test Group A - Accelerated Environment Stress Tests</b>													
PC	A1	JEDEC J-STD-020 JE5022-A113	3	77	Preconditioning	MSL1 260C	-	-	-	3/Pass	3/Pass	3/Pass	3/Pass
HAST	A2	JEDEC JE5022-A110	3	77	Biased HAST	180C/85%RH	96 Hours	-	-	3/231/0	3/231/0	3/231/0	3/231/0
AC/UHAST	A3	JEDEC JE5022-A102/JEDEC JE5022-A118	3	77	Autoclave	121C/15psi	96 Hours	-	-	3/231/0	3/231/0	3/231/0	-
AC/UHAST	A3	JEDEC JE5022-A102/JEDEC JE5022-A118	3	77	Unbiased HAST	180C/85%RH	96 Hours	-	-	-	-	3/231/0	3/231/0
TC	A4	JEDEC JE5022-A104 and Appendix 3	3	77	Temperature Cycle	-55C/150C	1500 Cycles	-	-	-	-	-	3/231/0
TC	A4	JEDEC JE5022-A104 and Appendix 3	3	77	Temperature Cycle	-55C/150C	500 Cycles	-	-	3/231/0	3/231/0	3/231/0	3/231/0
TC-BP	A4	MIL-STD-883 Method 2011	1	5	Post Temp Cycle Bond Pull	-	-	-	-	3/15/0	3/15/0	3/15/0	3/15/0
HTSL	A6	JEDEC JE5022-A103	1	45	High Temperature Storage Life	150C	1000 Hours	-	-	-	3/135/0	3/135/0	-
HTSL	A6	JEDEC JE5022-A103	1	45	High Temperature Storage Life	175C	500 Hours	-	-	3/135/0	-	3/135/0	-
<b>Test Group B - Accelerated Lifetime Simulation Tests</b>													
HTOL	B1	JEDEC JE5022-A108	3	77	Life Test	125C	1000 Hours	-	-	-	-	3/231/0	3/231/0
HTOL	B1	JEDEC JE5022-A108	3	77	Life Test	150C	1000 Hours	3/231/0	3/231/0	-	-	-	-
HTOL	B1	JEDEC JE5022-A108	3	77	Life Test	150C	300 Hours	-	-	-	3/231/0	-	-
HTOL	B1	JEDEC JE5022-A108	3	77	Life Test	150C	408 Hours	-	-	3/231/0	-	-	-
HTRB	B1.1	MIL-STD-750-1	3	77	High Temperature Reverse Bias	150C	1000 Hours	-	-	-	-	-	1/77/0
ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate	125C	48 Hours	-	-	-	-	-	3/2400/0
ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate	150C	24 Hours	-	-	3/2400/0	-	-	-
ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate	150C	48 Hours	3/2400/0	3/2400/0	-	-	-	-
EDR	B3	AEC Q100-005	1	77	NVM Endurance, Data Retention, and Up Life	Per QSS-009-018	1 Step	1/77/0	-	-	-	-	-
<b>Test Group C - Package Assembly Integrity Tests</b>													
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	-	-	3/15/0	3/90/0	1/30/0	3/90/0
WBP	C2	MIL-STD-883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	-	-	3/15/0	3/90/0	1/30/0	3/90/0
RSH	C8	JE5022-B107	-	30	Solder Heat	260C, 10 seconds	1 Step	-	-	-	-	-	1/30/0
SD	C3	JEDEC J-STD-002	1	15	PB Solderability	>95% Lead Coverage	-	-	-	1/15/0	1/15/0	1/15/0	1/15/0
SD	C3	JEDEC J-STD-002	1	15	PB-Free Solderability	>95% Lead Coverage	-	-	-	1/15/0	1/15/0	1/15/0	1/15/0
PD	C4	JEDEC JE5022-B100 and B108	3	10	Physical Dimensions	Cpk>1.67	-	-	-	3/30/0	3/30/0	1/10/0	3/30/0

Test Group D - Die Fabrication Reliability Tests													
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements					
TDOB	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements					
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements					
BTI	D4	-	-	-	Bias Temperature Instability	-	-	Completed Per Process Technology Requirements					
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements					

  

Test Group E - Electrical Verification Tests														
ED	ES	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	3/9/0	3/9/0	3/9/0	3/9/0	1/25/0

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

#### Ambient Operating Temperature by Automotive Grade Level:

Grade 0 (or E): -40C to +150C

Grade 1 (or Q): -40C to +125C

Grade 2 (or T): -40C to +105C

Grade 3 (or I) : -40C to +85C

#### E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

Room/Hot/Cold : HTOL, ED

Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU

Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2507-022

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

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